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# High Current, High Frequency, Power Inductors

## FLAT-PAC™ FP1109 Series



### Description:

- Halogen free
- 125°C maximum total temperature operation
- 11.2 x 11.2 x 9.0mm maximum surface mount package
- Ferrite core material
- High current carrying capacity, low core losses
- Controlled DCR tolerance for sensing circuits
- Inductance range from 205nH to 950nH
- Current range from 11.5 to 69 amps
- Frequency range up to 2MHz
- RoHS compliant

### Applications:

- Multi-phase regulators
- Voltage Regulator Module (VRM)
- Desktop and server VRMs and EVRDs
- Data networking and storage systems
- Graphics cards and battery power systems
- Point-of-load modules
- DCR sensing
- Notebook regulators

### Environmental Data:

- Storage temperature range: -40°C to +125°C
- Operating temperature range: -40°C to +125°C (ambient plus self temperature rise)
- Solder reflow temperature: J-STD-020D compliant

### Packaging:

- Supplied in tape and reel packaging, 350 parts per reel, 13" diameter reel

Product Specifications							
Part Number <sup>7</sup>	OCL <sup>1</sup> ± 20% (nH)	FLL <sup>2</sup> Min. (nH)	I <sub>rms</sub> <sup>3</sup> (Amps)	I <sub>sat</sub> <sup>4</sup> @ 25°C (Amps)	I <sub>sat</sub> <sup>25</sup> @ 125°C (Amps)	DCR (mΩ) @ 20°C	K-factor <sup>6</sup>
FP1109-R20-R	205	122	35	69	52	0.42 ±10%	233
FP1109-R23-R	247	147		55	41		233
FP1109-R27-R	270	160		51	38		233
FP1109-R33-R	311	185		44	33		233
FP1109-R47-R	463	275		27	20		233
FP1109-R58-R	548	325		22.5	17		233
FP1109-1R0-R	950	565		11.5	8.5		233

1 Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.10V<sub>rms</sub>, 0.0Adc

2 Full Load Inductance (FLL) Test Parameters: 100kHz, 0.1V<sub>rms</sub>, I<sub>sat</sub><sup>1</sup>

3 I<sub>rms</sub>: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed 125°C under worst case operating conditions verified in the end application.

4 I<sub>sat</sub><sup>1</sup>: Peak current for approximately 30% rolloff at +25°C.

5 I<sub>sat</sub><sup>25</sup>: Peak current for approximately 30% rolloff at +125°C.

6 K-factor: Used to determine B<sub>p-p</sub> for core loss (see graph). B<sub>p-p</sub> = K · L · ΔI · 10<sup>-3</sup>, B<sub>p-p</sub>: (Gauss), K: (K-factor from table), L: (inductance in nH), ΔI (peak-to-peak ripple current in amps).

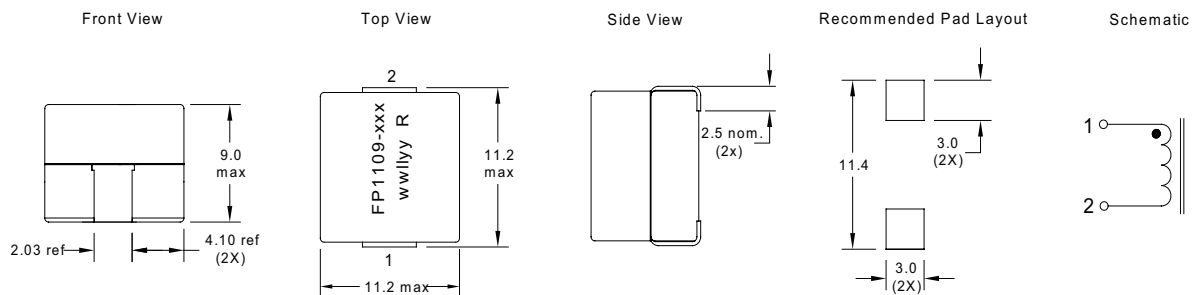
7 Part Number Definition: FP1109-xxx-R

• FP1109 = Product code and size

• xxx= Inductance value in μH, R = decimal point. If no "R" is present, then third character = # of zeros

• "-R" suffix = RoHS compliant

### Dimensions - mm



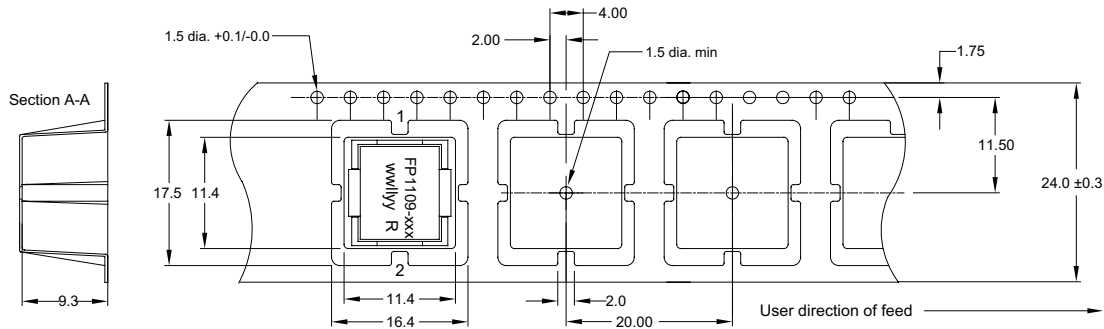
Part Marking: FP1109

xxx = Inductance value in  $\mu\text{H}$ . (R = Decimal point). If no "R" is present, then last character is # of zeros

wwllly = Date code

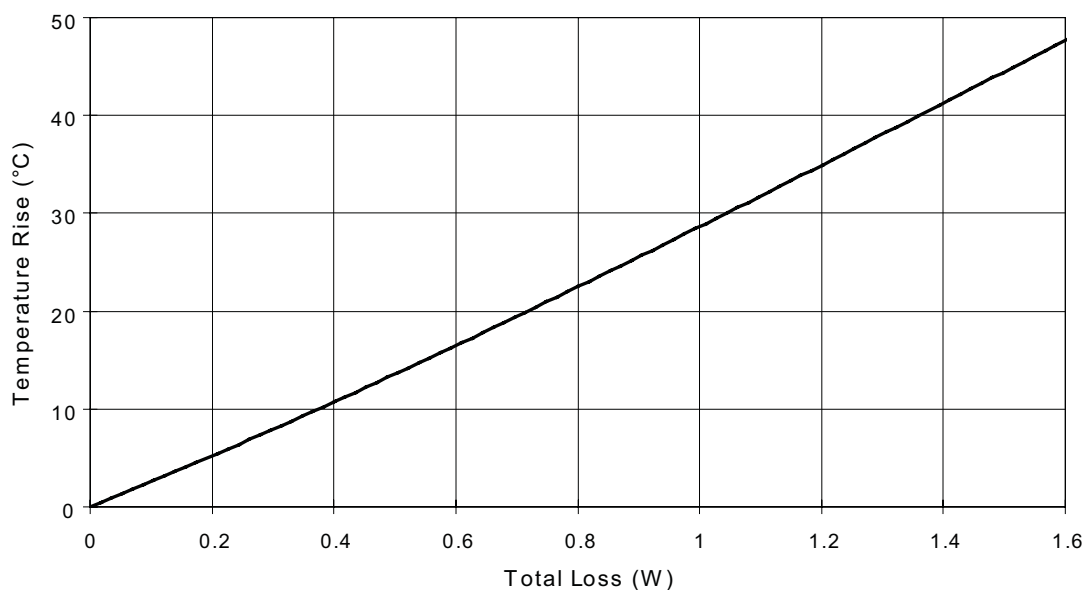
R = Revision level

### Packaging Information - mm



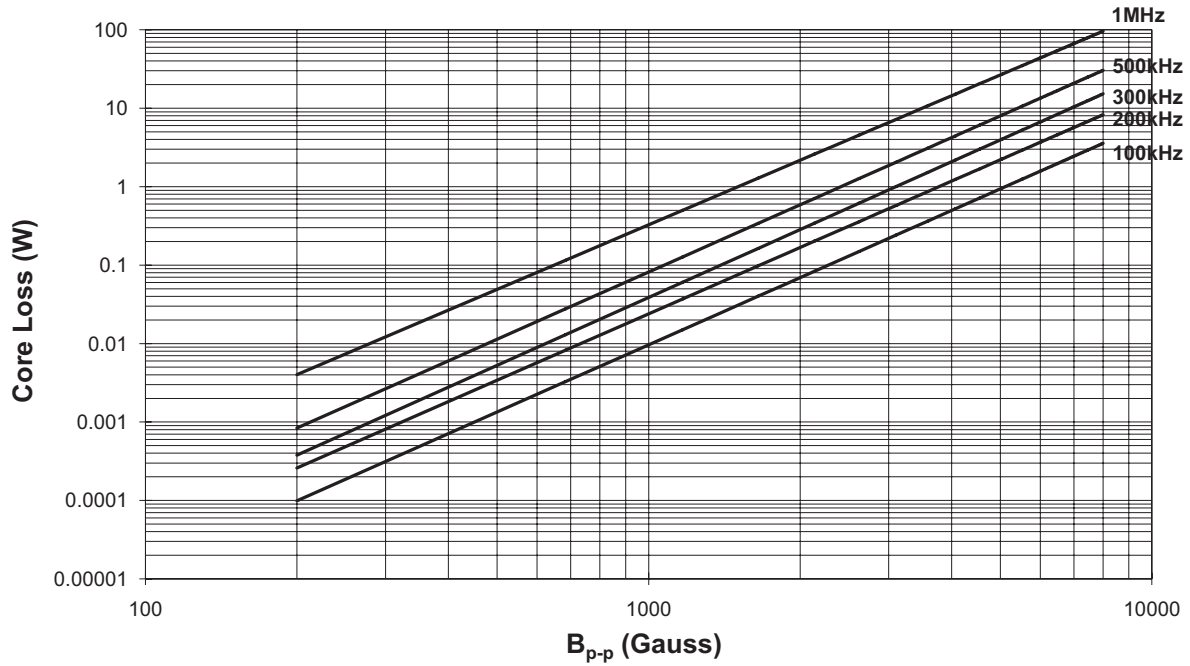
Supplied in tape-and-reel packaging, 350 parts per reel, 13" diameter reel.

### Temperature Rise vs. Total Loss



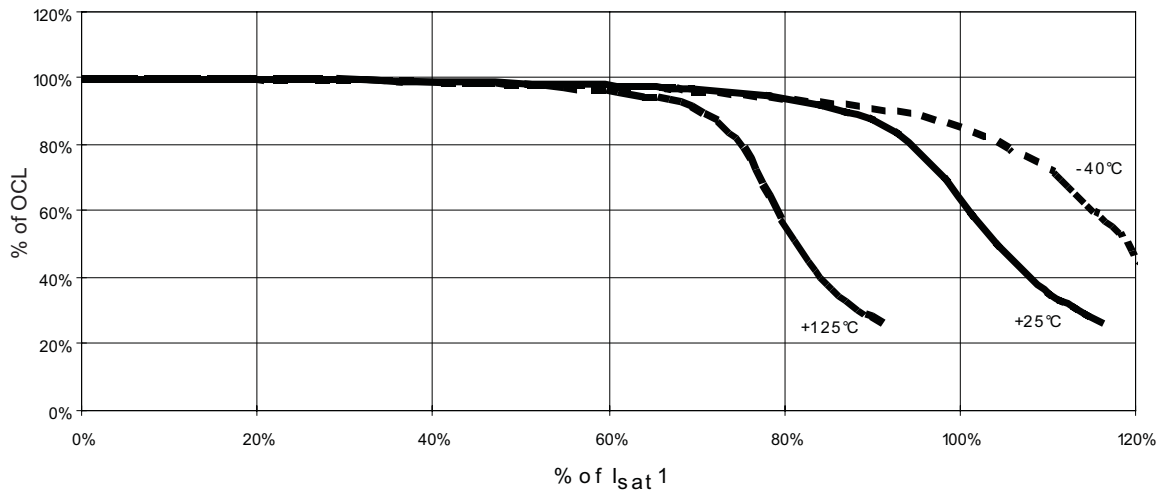
## Core Loss

### Core Loss vs. $B_{p-p}$



## Inductance Characteristics

### % of OCL vs. % of $I_{sat1}$



## Solder Reflow Profile

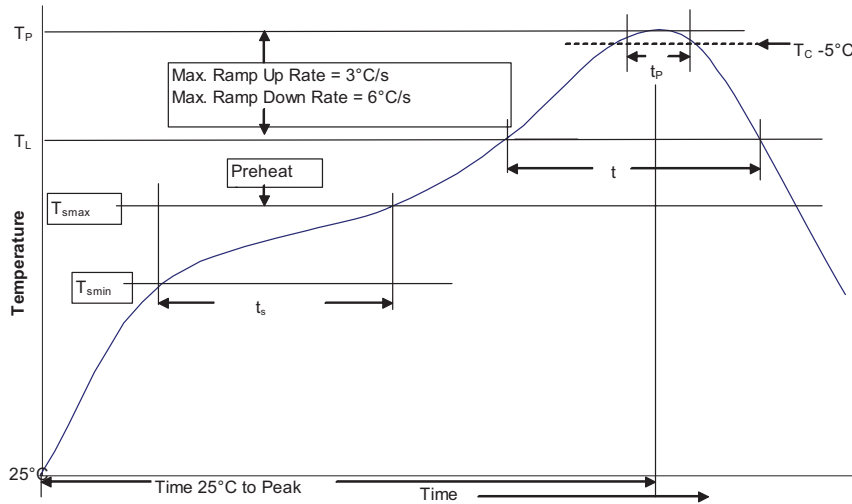


Table 1 - Standard SnPb Solder ( $T_c$ )

Package Thickness	Volume $\text{mm}^3$ <350	Volume $\text{mm}^3$ $\geq$ 350
<2.5mm	235°C	220°C
$\geq$ 2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder ( $T_c$ )

Package Thickness	Volume $\text{mm}^3$ <350	Volume $\text{mm}^3$ 350 - 2000	Volume $\text{mm}^3$ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

## Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. ( $T_{smin}$ )	100°C	150°C
• Temperature max. ( $T_{smax}$ )	150°C	200°C
• Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 Seconds	60-120 Seconds
Average ramp up rate $T_{smax}$ to $T_p$	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature ( $T_L$ )	183°C	217°C
Time at liquidous ( $t_L$ )	60-150 Seconds	60-150 Seconds
Peak package body temperature ( $T_p$ )*	Table 1	Table 2
Time ( $t_p$ )** within 5 °C of the specified classification temperature ( $T_c$ )	20 Seconds**	30 Seconds**
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

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